

This listing of claims will replace all prior versions of claims in the Application.

Listing of Claims

Claim 1. (Currently Amended) A method of providing a metal seed layer substantially free of discontinuities disposed on a substrate comprising the ~~step~~-~~steps~~ of contacting a metal seed layer having discontinuities disposed on a substrate with an electroplating bath comprising a) a source of metal ions; b) an electrolyte comprising two ~~or more~~ acids; c) and optionally one or more additives; wherein the two acids are present in a ratio of 99:1 to 1:99 by weight; and applying a current.

Claim 2. (Currently Amended) The method of claim 1 wherein the two or more acids are selected from organic acids, inorganic acids, ~~or~~-and mixtures thereof.

Claim 3. (Currently Amended) The method of claim 2 wherein the organic acids are selected from alkylsulfonic acids, aryl sulfonic acids, carboxylic acids ~~or~~-and halogenated acids.

Claim 4. (Currently Amended) The method of claim 2 wherein the inorganic acids are selected from sulfuric acid, phosphoric acid, nitric acid, hydrogen halide acids, sulfamic acid ~~or~~ and fluoroboric acid.

Claim 5. (Currently Amended) The method of claim 1 wherein the ~~two or more~~ acids are present in ~~an~~-a total amount of from about 1 to about 350 g/L.

Claim 6. (Original) The method of claim 1 wherein the source of metal ions is a source of copper ions.

Claim 7. (Currently Amended) The method of claim 6 wherein the source of copper ions is selected from copper sulfates, copper acetates, copper fluoroborate, ~~or~~-and cupric nitrates.

Claim 8. (Original) The method of claim 6 wherein the source of copper ions is present in an amount of from about 1 to about 300 g/L.

Claim 9. (Original) The method of claim 1 wherein the electrolyte further comprises a source of halide ions.

Claim 10. (Currently Amended) A method of manufacturing an electronic device comprising the ~~step~~-~~steps~~ of contacting a metal seed layer having discontinuities disposed on a

substrate with an electroplating bath comprising a) a source of metal ions; b) an electrolyte comprising two or more acids; c) and optionally one or more additives; wherein the two acids are present in a ratio of 99:1 to 1:99 by weight; and applying a current.

Claim 11. (Currently Amended) The method of claim 10 wherein the two or more acids are selected from organic acids, inorganic acids, or and mixtures thereof.

Claim 12. (Currently Amended) The method of claim 11 wherein the organic acids are selected from alkylsulfonic acids, aryl sulfonic acids, carboxylic acids or and halogenated acids.

Claim 13. (Currently Amended) The method of claim 11 wherein the inorganic acids are selected from sulfuric acid, phosphoric acid, nitric acid, hydrogen halide acids, sulfamic acid or and fluoroboric acid.

B3
Contd. Claim 14. (Currently Amended) The method of claim 10 wherein the ~~two or more~~ acids are present in ~~an~~ a total amount of from about 1 to about 350 g/L.

Claim 15. (Original) The method of claim 10 wherein the source of metal ions is a source of copper ions.

Claim 16. (Currently Amended) The method of claim 15 wherein the source of copper ions is selected from copper sulfates, copper acetates, copper fluoroborate, or and cupric nitrates.

Claim 17. (Original) The method of claim 15 wherein the source of copper ions is present in an amount of from about 1 to about 300 g/L.

Claim 18. (Original) The method of claim 10 wherein the electrolyte further comprises a source of halide ions.

Claims 19-22. (Canceled)

Claim 23. (New) The method of claim 1 wherein the electroplating bath comprises three or more acids.

Claim 24. (New) The method of claim 10 wherein the electroplating bath comprises three or more acids.